Tengfei Jiang

List of Publications by Year
in descending order

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Version: 2024-02-01

17	537	1307594 7	1372567 10
papers	citations	h-index	g-index

17	17	17	1123
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	The Effects of Bi Doping and Aging on Viscoplasticity of Sn-Ag-Cu-Bi alloys. , 2022, , .		0
2	<i>In situ</i> TEM Characterization of Microstructure Evolution and Mechanical Behavior of the 3D-Printed Inconel 718 Exposed to High Temperature. Microscopy and Microanalysis, 2021, 27, 250-256.	0.4	7
3	Application of Machine Learning in Recognition and Analysis of TSV Extrusion Profiles with Multiple Morphology. , 2021, , .		2
4	The Effect of Pitch Distance on the Statistics and Morphology of Through-Silicon Via Extrusion. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 883-891.	2.5	5
5	Effect of Wiring Density and Pillar Structure on Chip Packaging Interaction for Mixed-Signal Cu Low k Chips. IEEE Transactions on Device and Materials Reliability, 2021, 21, 290-296.	2.0	10
6	Study of the Impact of Pitch Distance on the Statistical Variation of TSV Protrusion and the Underlying Mechanisms. , 2020, , .		6
7	Micro-Compression of Freestanding Electroplated Copper Through-Glass Vias. IEEE Transactions on Device and Materials Reliability, 2020, 20, 199-203.	2.0	2
8	Synchrotron X-Ray Microdiffraction Investigation of Scaling Effects on Reliability for Through-Silicon Vias for 3-D Integration. IEEE Transactions on Device and Materials Reliability, 2019, 19, 568-571.	2.0	10
9	Long-Term Reliability of Solder Joints in 3D ICs Under Near-Application Conditions. , 2019, , .		2
10	The effective control of Cu through-silicon via extrusion for three-dimensional integrated circuits by a metallic cap layer. Scripta Materialia, 2019, 164, 101-104.	5.2	7
11	Study of the Effect and Mechanism of a Cap Layer in Controlling the Statistical Variation of Via Extrusion. , 2019, , .		4
12	Study of the Long Term Reliability of 3D IC under Near-Application Conditions. , 2018, , .		2
13	Effect of scaling copper through-silicon vias on stress and reliability for 3D interconnects. , 2016, , .		9
14	Quantitative microstructural imaging by scanning Laue x-ray micro- and nanodiffraction. MRS Bulletin, 2016, 41, 445-453.	3.5	38
15	Oxygen-activated growth and bandgap tunability of large single-crystal bilayer graphene. Nature Nanotechnology, 2016, 11, 426-431.	31.5	287
16	Through-silicon via stress characteristics and reliability impact on 3D integrated circuits. MRS Bulletin, 2015, 40, 248-256.	3.5	50
17	Measurement and analysis of thermal stresses in 3D integrated structures containing through-silicon-vias. Microelectronics Reliability, 2013, 53, 53-62.	1.7	96